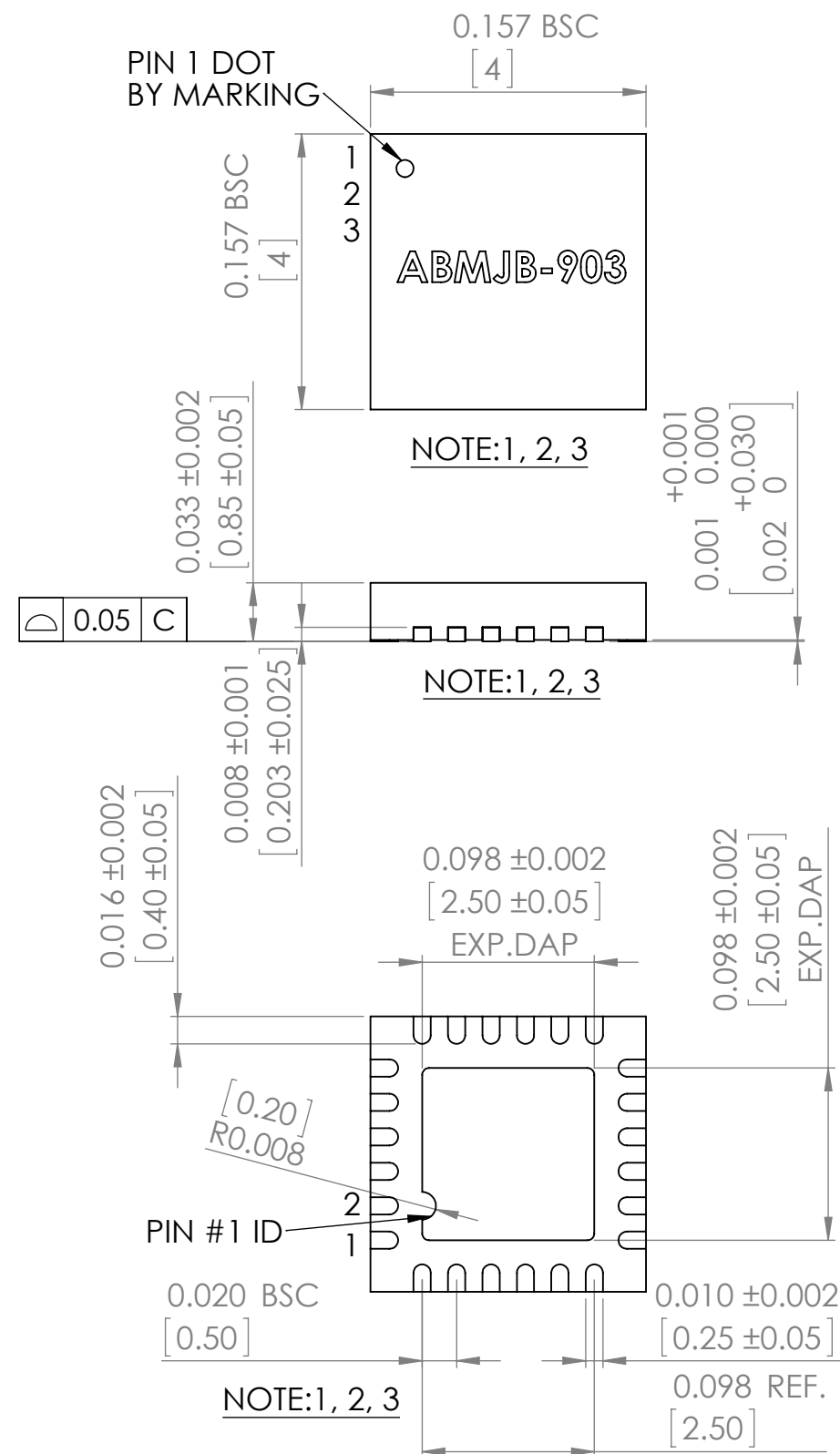
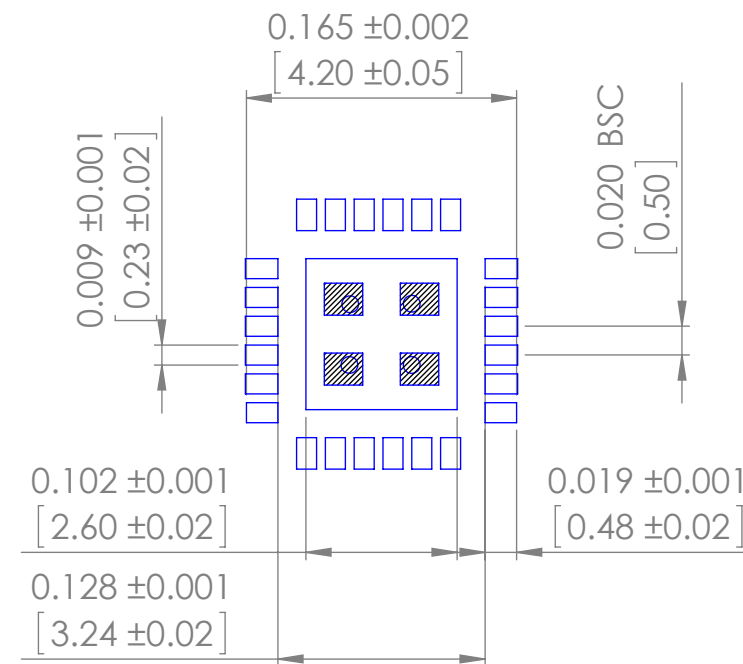
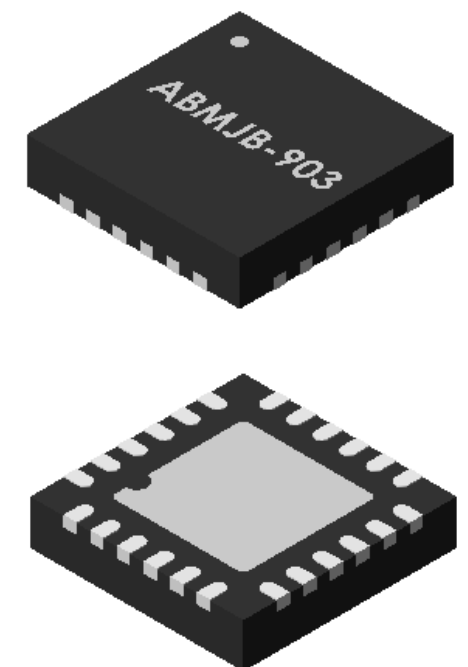




Recommended Land Pattern



Pin No.	Configuration.
22	Q
23	/Q
3	REFIN
12	OE
1,20	VDD
17,24	VDDO
2,8,13,14 15,21	VSS
4,5,7,9 11,16,18	DNC
6,10,19	DNC
ePad	Exposed Pad



Notes:

1. Max Package warpage is 0.05mm.
2. Max allowable burr is 0.076mm in all directions.
3. Pin 1 is on top and will be laser marked.
4. Red circles in land pattern indicate thermal vias. Size should be 0.30-0.35M in diameter and should be connected to GND for max thermal performance.
5. Green rectangles (shaded area) indicate solder stencil opening on exposed pad area. Size should be 1.00 x 1.00 mm in size, 1.20mm pitch.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCH(MM) SURFACE FINISH: TOLERANCES: LINEAR: ANGULAR:				FINISH:		DEBUR AND BREAK SHARP EDGES		DO NOT SCALE DRAWING		REVISION -	
DRAWN -				SIGNATURE		DATE		 30332 Esperanza, Rancho Santa margarita, California 92688			
CHK'D XXXXXX				SIGNATURE		DATE		TITLE:			
APPV'D				SIGNATURE		DATE		DWG NO. ABMJB-903			
MFG				SIGNATURE		DATE		A3			
Q.A				SIGNATURE		DATE		SCALE: 10:1 SHEET 1 OF 1			
				MATERIAL:		WEIGHT:					